

ABSTRACT

Embodiments of the present disclosure disclose a method and device for planning a wall surface polishing path, an apparatus and medium. The method includes: obtaining protruding points of a wall surface to be polished, and dividing the wall surface to be polished into at least two regions; determining a candidate protruding point in the next region of the region where a current protruding point is located; comparing, if the region where the current protruding point is located includes an untraversed protruding point, a first distance between the untraversed protruding point and the current protruding point, with a second distance between the candidate protruding point and the current protruding point; determining the protruding point corresponding to a minimum distance in the first distance and the second distance as a next operation point of the current protruding point; and determining the wall surface polishing path based on the current protruding point and the next operation point of the current protruding point. The technical solution in the embodiments of the present disclosure solves the problem that a polishing path of a current polishing device covers a region with no need for polishing, and achieves effects of optimizing an operation path of a polishing device, improving polishing efficiency, and reducing polishing costs.